

SMALL SIGNAL SCHOTTKY DIODE

DESCRIPTION

Metal to silicon junction diode featuring high breakdown, low turn-on voltage and ultrafast switching.

Primarly intended for high level UHF/VHF detection and pulse application with broad dynamic

Matched batches are available on request.



ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit			
V_{RRM}	Repetitive Peak Reverse Voltage	70	V			
l _F	Forward Continuous Current* T _a = 2.5 C	5	mA			
I _{FSM}	Surge non Repetitive Forward Current* ι _p ≤ 1s 50					
T _{stg} T _j	Storage and Junction Temperature Range	- 65 to 200 - 65 to 200	°C			
TL	Maximum Lead Temperaturs for Soldering during its at 4mm from Case	230	°C			

THERMAL RESISTANCE

Symbol	Test Conditions	Value	Unit
R _{th(j-a)}	Junction-ambient*	400	°C/W

ELECTPICAL CHARACTERISTICS

STATIC CHARACTERISTICS

1	Symbol	Test Conditions	Тур.	Max.	Unit	
	V_{BR}	$T_{a_{1110}} = 25^{\circ} CI_{R} = 10 \mu A$	70			V
	V _F * *	$T_{amb} = 25$ °CI _F = 1mA			0.41	V
	250	$T_{amb} = 25$ °CI _F = 15mA			1	
1	I _R * *	$T_{amb} = 25^{\circ}CV_{R} = 50V$			0.2	μΑ

DYNAMIC CHARACTERISTICS

Symbol	Test Conditions	Max.	Unit	
С	$T_{amb} = 25$ °CV _R = 0Vf = 1MHz		2	pF
τ	T _{amb} = 25°CI _F = 5mA Krakauer Method		100	ps

* On infinite heatsink with 4mm lead length
** Pulse test: $t_{p} \ @ 300 \mu s \ \delta < 2\%$.
Matched batches available on request. Test conditions (forward voltage and/or capacitance) according to customer specification.

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Fig. 1: Forward current versus forward voltage at low level (typical values).

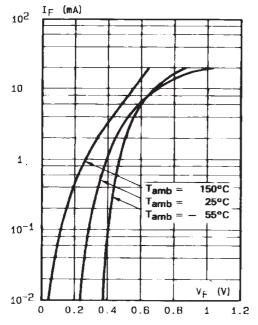


Fig. 2: Capacitance C versus reverse applied voltage V_R (typical values).

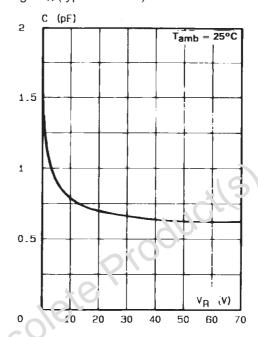


Fig. 3: Reverse current versus ambie. It temperature.

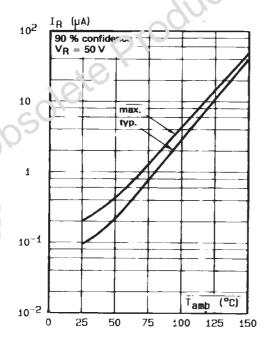
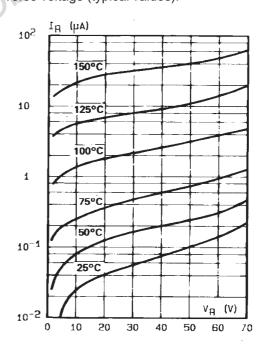


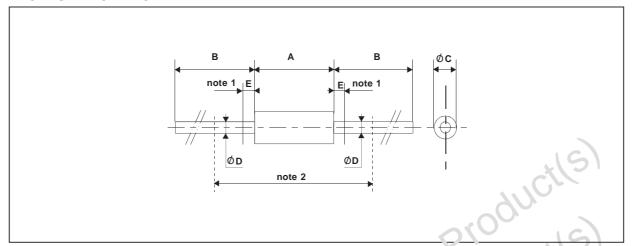
Fig. 4: Reverse current versus continuous reverse voltage (typical values).



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Cooling method: by convection and conduction Marking: clear, ring at cathode end.

PACKAGE MECHANICAL DATA



DIMENSIONS NOTES			NOTES		
REF.	F. Millimeters Inch		hes	alera adio	
	Min.	Max.	Min.	Max.	anso pro
Α	3.050	4.500	0.120	0.117	1 - The Nad diameter Ø D is not controlled over zone E
В	12.7		0.500		2 - The minimum axial lengh within which the device may be
ØC	1.530	2.000	0.060	0.079	praced with its leads bent at right angles is 0.59"(15 mm)
ØD	0.458	0.558	0.013	t u22	OS
Е		1.27	0	0.050	
105°C	iet ^e	s P	, od	uct	

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